



Material Content Data Sheet



Sales Product Name		IPG20N06S2L-50A		Issued		1. August 2018		
MA#		MA002213662						
Package		PG-TDSON-8-10		Weight*		98.99 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	1.164	1.18	1.18	11758	11758
chip_2	inorganic material	silicon	7440-21-3	1.164	1.18	1.18	11758	11758
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		141	
	non noble metal	iron	7439-89-6	0.046	0.05		469	
	non noble metal	copper	7440-50-8	46.380	46.84	46.90	468560	469170
	non noble metal	aluminium	7429-90-5	0.821	0.83	0.83	8296	8296
wire	non noble metal	aluminium	7429-90-5	0.821	0.83	0.83	8296	8296
encapsulation	organic material	carbon black	1333-86-4	0.089	0.09		902	
	plastics	epoxy resin	-	6.340	6.41		64055	
	inorganic material	silicondioxide	60676-86-0	38.221	38.61	45.11	386132	451089
leadfinish	non noble metal	tin	7440-31-5	1.396	1.41	1.41	14107	14107
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		15	
	non noble metal	nickel	7440-02-0	0.603	0.61	0.61	6093	6108
solder	non noble metal	tin	7440-31-5	0.055	0.06		554	
	noble metal	silver	7440-22-4	0.069	0.07		693	
	non noble metal	lead	7439-92-1	2.620	2.65	2.78	26467	27714
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com